

SPECIFICATION
LCD MODULE
P032H005
REVISION RECORD

DESIGN	CHECK	REVIEW
VERSION	DATE	CONTENTS
A	2016-09-18	First Release

CUSTOMER












Customer company:

Date:

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GENERAL INFORMATION

Item	Contents	Unit
Driver element	a-Si 3.2 TFT active matrix	--
Viewing direction	Wide	O' Clock
LCM OUTLINE DIMENSIONS	55.04(W) x 77.5(H) x 3.7(T)	mm
Active area (W×H)	48.6(H) × 64.8(V)MM	mm
Number of Dots	240RGB(H)×320(V)	Pixel
Driver IC	ILI9341V	--
Colors	262K	--
Weight	TBD	g
Backlight Type	LED	--
Interface Type	8 /16bits parallel interface	--
Input voltage	2.8	V

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	3.3	V
Input voltage	VIN	-0.3	VDD+0.3	V
Operating temperature	TOP	-20	70	°C
Storage temperature	TST	-30	80	°C
Humidity	RH		90% (Max60°C)	RH

ELECTRICAL CHARACTERISTICS

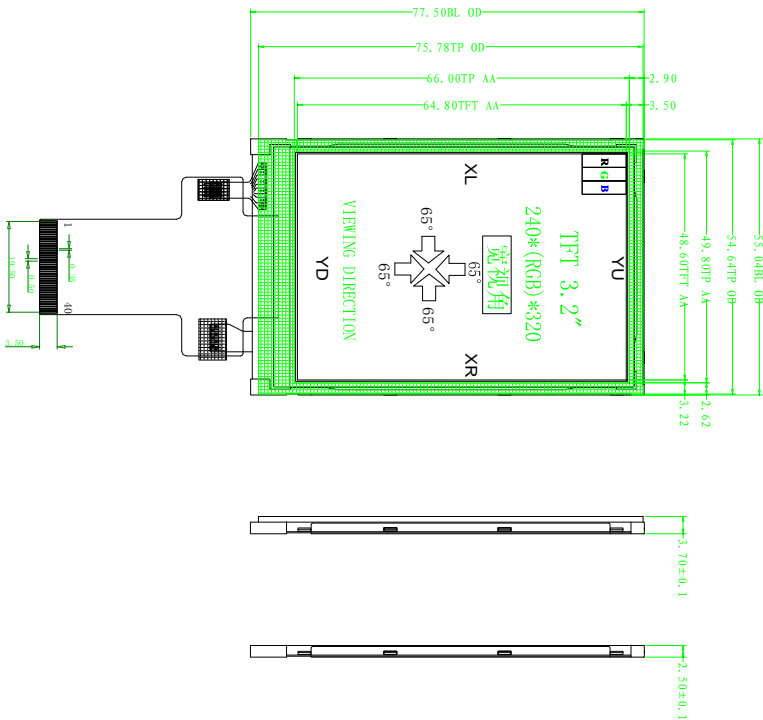
DC CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage for analog	VDD	2.3	2.8	3.3	V
Input Current	Idd	—	—	—	mA
Supply voltage for I/O circuit	IOVCC	1.65	1.8	3.3	V
Input voltage ' H' level	VIH	0.7 IOVCC	—	—	V
Input voltage ' L' level	VIL	—	—	0.3 IOVCC	V
Output voltage ' H' level	VOH	0.8 IOVCC	—	—	V
Output voltage ' L' level	VOL	—	—	0.2 IOVCC	V

BACKLIGHT CHARACTERISTICS

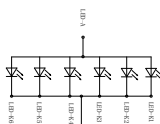
Item	Symbol	Min	Typ	Max	Unit	Condition
Forward voltage	Vf	2.8	3.2	3.3	V	If=90 mA
Luminance	Lv	6800		--	cd/m²	
Number of LED	—	6			Piece	—
Connection mode	p	Parallel			—	—

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注意PC+PI补强 0.3 ± 0.03

1	XL	21	DB4
2	YU	22	DB5
3	XR	23	DB6
4	YD	24	DB7
5	GND	25	DB8
6	IOVCC	26	DB9
7	VCC	27	DB10
8	PMARK	28	DB11
9	CS	29	DB12
10	RS	30	DB13
11	WR	31	DB14
12	RD	32	DB15
13	SDA	33	LEDA
14	SDD	34	LEDK
15	RESET	35	LEDK
16	GND	36	LEDK
17	DB0	37	GND
18	DB1	38	IM0
19	DB2	39	IM1
20	DB3	40	IM2



GENERAL TOLERANCE										SIZE	A4	DRAWING	MODEL	TITLE	MODULE DRAWING	P03ZH005
STEP	1	2	3	UNIT			mm	DESIGN	CHECKED	DWG NO.	P03ZH005	DATE	2016. 09. 18	REV	A1	
0<K4	±0.05	±0.10	±0.20	SCALE			1 : 1									
4<K16	±0.08	±0.15	±0.30	SHEET			1	OF 1	APPR.							
16<K48	±0.12	±0.25	±0.50	TOLERANCE			LEVEL 2									
64<K56	±0.25	±0.40	±0.80	3rd ANGLE PROJECTION												
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PIN No.	Symbol	Description
1	X(L)	Touch panel control pin (触摸屏控制脚)
2	Y(U)	Touch panel control pin (触摸屏控制脚)
3	X(R)	Touch panel control pin (触摸屏控制脚)
4	Y(D)	Touch panel control pin (触摸屏控制脚)
5	GND	Ground (接地脚)
6	IOVCC	Power supply for LCM (2.8V-3.3V) (屏供电脚)
7	VCI	Power supply for LCM (2.8V-3.3V) (屏供电脚)
8	FMARK	Tearing effect output pin to synchronize MPU to frame writing, activated by S/W command. When this pin is not activated, this pin is low. If not used, open this pin. (帧同步信号, 不用时悬空)
9	CS/SPI CS	Chip select pin ("Low" enable) (屏驱动芯片片选脚, 低电平有效)
10	RS/SPI SCL/SCK	This pin is used to select "Data or Command" in the parallel interface or serial data interface. (用于并口或者串口) Parallel(并口): When RS= '1', data is selected.(选择数据) When RS= '0', command is selected.(选择寄存器) Serial(串口): This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. (3线串口或者4线串口的时钟信号)

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		If not used, this pin should be connected to IOVCC or GND. (不用时接 IOVCC 或者接地)
11	WR/AO (4 线)	Serves as a write signal and writes data at the rising edge. - 4-line system (D/CX): Serves as command or parameter select. <i>Fix to IOVCC level when not in use</i> (并口的写控制脚或者 4 线串口的寄存器/数据选择, 不用时接 IOVCC)
12	RD	Serves as a read signal and MCU read data at the rising edge. <i>Fix to IOVCC level when not in use</i> (并口的读控制脚, 不用时接 IOVCC)
13	SPI SDI/SDA	Serial input signal. The data is applied on the rising edge of the SCL signal. <i>If not used, fix this pin at IOVCC or GND</i> (串口数据输入信号, 不用时接 IOVCC 或者接地)
14	SPI SDO	Serial output signal. The data is outputted on the falling edge of the SCL signal. <i>If not used, open this pin</i> (串口数据输出信号, 不用时悬空)
15	RESET	LCM Reset pin Signal is active low. (屏复位脚, 低电平复位)
16	GND	Ground (接地脚)
17-24	DB0-DB7	Data bus <i>Fix to GND level when not in use</i> (低 8 位数据线, 不用时接地)
25-32	DB8-DB15	Data bus <i>Fix to GND level when not in use</i> (高 8 位数据线, 不用时接地)
33	A	Anode of Backlight (3.0V-3.4V Typical:3.2V) (背光正极供电脚, 电压范围:3.0-3.4V, 典型值:3.2V)
34-36	K	Cathode of Backlight (背光负极供电脚)
37	GND	Ground (接地脚)

38	IM0	Select the MCU interface mode (接口选择) IM2 IM1 IM0																																				
		<table><tr><td>0</td><td>0</td><td>0</td><td>80 MCU 16-bit bus interface []</td><td>D[8:1]</td><td>D[17:10], D[8:1]</td></tr><tr><td>0</td><td>0</td><td>1</td><td>80 MCU 8-bit bus interface []</td><td>D[17:10]</td><td>D[17:10]</td></tr><tr><td>0</td><td>1</td><td>0</td><td>80 MCU 18-bit bus interface []</td><td>D[8:1]</td><td>D[17:0]</td></tr><tr><td>0</td><td>1</td><td>1</td><td>80 MCU 9-bit bus interface []</td><td>D[17:10]</td><td>D[17:9]</td></tr><tr><td>1</td><td>0</td><td>1</td><td>3-wire 9-bit data serial interface []</td><td colspan="2">SDI: In SDO: Out</td></tr><tr><td>1</td><td>1</td><td>0</td><td>4-wire 8-bit data serial interface []</td><td colspan="2">SDI: In SDO: Out</td></tr></table>	0	0	0	80 MCU 16-bit bus interface []	D[8:1]	D[17:10], D[8:1]	0	0	1	80 MCU 8-bit bus interface []	D[17:10]	D[17:10]	0	1	0	80 MCU 18-bit bus interface []	D[8:1]	D[17:0]	0	1	1	80 MCU 9-bit bus interface []	D[17:10]	D[17:9]	1	0	1	3-wire 9-bit data serial interface []	SDI: In SDO: Out		1	1	0	4-wire 8-bit data serial interface []	SDI: In SDO: Out	
0	0	0	80 MCU 16-bit bus interface []	D[8:1]	D[17:10], D[8:1]																																	
0	0	1	80 MCU 8-bit bus interface []	D[17:10]	D[17:10]																																	
0	1	0	80 MCU 18-bit bus interface []	D[8:1]	D[17:0]																																	
0	1	1	80 MCU 9-bit bus interface []	D[17:10]	D[17:9]																																	
1	0	1	3-wire 9-bit data serial interface []	SDI: In SDO: Out																																		
1	1	0	4-wire 8-bit data serial interface []	SDI: In SDO: Out																																		
39	IM1																																					
40	IM2	NOTE: D[8:1]即低 8 位数据线 DB7-DB0D D[17:10]即高 8 位数据线 DB15-DB8																																				

关于供电说明:

IOVCC 和 VCC 连一起, 用 2.8V-3.3V 供电; 背光 LED 可以单独供电 (3.0-3.4 V), 也可以和 VCC 共用一组电压 (A 为正接 VCC, K 连一起作为负接地)。

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APPLICATION CIRCUIT

Please consult our technical department for detail information.

INITIAL CODE

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ELECTRO-OPTICAL CHARACTERISTICS

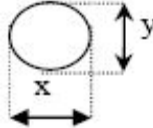
Item		Symbol	Condition	Min	Typ	Max	Unit	Remark	Note
Response time		Tr+Tf	$\theta = 0^\circ$ E=0° Ta=25°C	—	20	30	ms	FIG 1.	4
Contrast ratio		Cr		—	400	500	—	FIG 2.	1
Luminance uniformity		δ WHITE		—	—	—	%	FIG 2.	3
Surface Luminance		Lv		300	—	—	cd/m ²	FIG 2.	2
Viewing angle range		CR>10	E 3	60	65	—	deg	FIG 3.	6
			E 9	60	65	—	deg	FIG 3.	
			E 12	60	65	—	deg	FIG 3.	
			E 6	50	65	—	deg	FIG 3.	
CIE(x, y) chromaticity	Red	x	$\theta = 0^\circ$ E=0° Ta=25°C	0.586	0.636	0.686		FIG 2.	5
		y		0.273	0.323	0.373			
	Green	x		0.252	0.277	0.297			
		y		0.529	0.549	0.569			
	Blue	x		0.122	0.142	0.162			
		y		0.102	0.122	0.142			
	White	x		0.283	0.303	0.323			
		y		0.305	0.325	0.345			

4. Standards of inspection items

4.1 Major Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1.1	All functional defects	1.No display 2.Display abnormally 3.Missing vertical, horizontal segment 4.Short circuit 5. Back-light no lighting, flickering and abnormal lighting.	Major
4.1.2	Missing	Missing component	
4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	
4.1.4	linearity	No more than 1.5%	

4.2 Cosmetic Defect

Item No	Items to be inspected	Inspection Standard				Classification of defects
4.21	Clear Spots Black and white Spot defect Pinhole, Foreign Particle, polarizer Dirt	For dark/white spot, size Φ is defined as $\Phi = \frac{(x + y)}{2}$				Minor
		1				
		<div>Zone Size(mm)</div>	Acceptable Qty			
			A	B	C	
		$\Phi \leq 0.15$	Ignore		Ignore	
		$0.15 < \Phi \leq 0.20$	2			
		$0.20 < \Phi \leq 0.30$	1			
		$\Phi > 0.30$	0			
	Clear Spots TP Dirt	2				Minor
		<div>Zone Size(mm)</div>	Acceptable Qty			
			A	B	C	
		$\Phi \leq 0.15$	Ignore		Ignore	
		$0.15 < \Phi \leq 0.20$	2			
		$0.20 < \Phi \leq 0.30$	1			
		$\Phi > 0.30$	0			
		Dim Spots Circle shaped and dim edged defects	3			
	<div>Zone Size(mm)</div>		Acceptable Qty			
			A	B	C	
	$\Phi \leq 0.2$		Ignore		Ignore	
	$0.20 < \Phi \leq 0.40$		2			
	$0.40 < \Phi \leq 0.60$		1			
$\Phi > 0.60$	0					

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2 Cosmetic Defect

Item No	Items to be inspected	Inspection Standard					Classification of defects
4.2.2	Line defect Black line, White line, Foreign material on polarizer	Size(mm)		Acceptable Qty			Minor
		L (Length)	W (Width)	Zone			
				A	B	C	
		Ignore	$W \leq 0.01$	Ignore		Ignore	
		$L \leq 3.0$	$0.01 < W \leq 0.03$	2			
		$L \leq 3.0$	$0.03 < W \leq 0.05$	1			
			$W > 0.05$	0			
	Foreign material on TP film	The line can be seen after mobile phone in the operating condition:					Minor
		Size(mm)		Acceptable Qty			
		L (Length)	W (Width)	Zone			
				A	B	C	
		Ignore	$W \leq 0.03$	Ignore		Ignore	
		$L \leq 5.0$	$0.03 < W \leq 0.05$	3			
	$W > 0.05$	0					
4.2.3	Dim line defect Polarizer scratch TP film scratch	If the scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 4.2.2.					Minor
		If the scratch can be seen only in non-operating condition or some special angle, judge by the following.					
		Size(mm)		Acceptable Qty			
		L (Length)	W (Width)	Zone			
				A	B	C	
		Ignore	$W \leq 0.03$	Ignore		Ignore	
		$5.0 < L \leq 10.0$	$0.03 < W \leq 0.05$	2			
		$L \leq 5.0$	$0.05 < W \leq 0.08$	1			
	$W > 0.08$	0					
4.2.4	Polarize Air bubble	Air bubbles between glass & polarizer					Minor
		Zone Size(mm)	Acceptable Qty				
			A	B	C		
		$\Phi \leq 0.25$	Ignore		Ignore		
		$0.25 < \Phi \leq 0.5$	2				
		$\Phi > 0.50$	0				

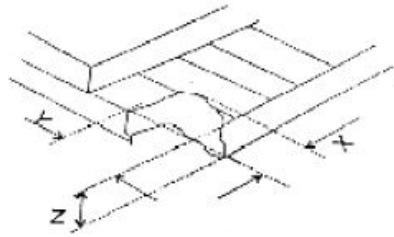
Item No	Items to be inspected	Inspection Standard	Classification of defects
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4.35

Glass defect

Minor

(i) Chips on corner
A:LCD Glass defect

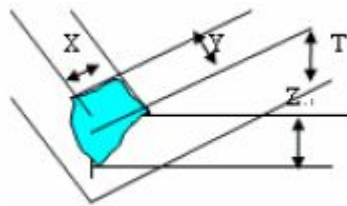


X (mm)	Y (mm)	Z (mm)
≤ 2.0	$\leq S$	Disregard

Notes: S=contact pad length

Chips on the corner of terminal shall not be allowed to extend into the ITO pad or expose perimeter seal.

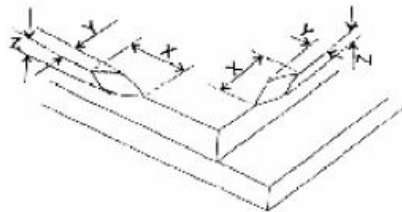
B:TP Glass defect



X (mm)	Y (mm)	Z (mm)
≤ 3.0	≤ 3.0	Disregard

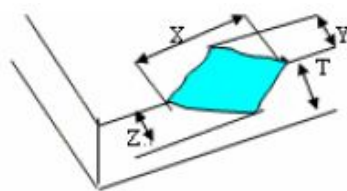
(ii) Usual surface cracks

A:LCD Glass defect



X (mm)	Y (mm)	Z (mm)
≤ 3.0	< Inner border line of the seal	Disregard

B:TP Glass defect



X (mm)	Y (mm)	Z (mm)
≤ 6.0	< 2.0	Disregard

(iii) Crack

Cracks tend to break are not allowed.

